



GomSpace A/S  
Langagervej 6  
9220 Aalborg E

## **NANOCOM ANT2150**

### Qualification Certificate

Reference: 1028496  
Revision: 1.2  
Date: 2024-05-01

|                  |   |                |            |
|------------------|---|----------------|------------|
| Document Title:  | NanoCom ANT2150 Qualification Certificate |                |            |
| Reference:       | 1028496                                   | Document Class | QTCT       |
| Revision number: | 1.2                                       | Date:          | 2024-05-01 |

**Release Table:**

| Action                  | Name                                      | Function                         | Initials / Signature | Date                     |
|-------------------------|---|----------------------------------|----------------------|--------------------------|
| Prepared / Owned by:    | Sebastian Andersen<br>Dannie Toft Nielsen | Junior Engineer<br>Test Engineer | SEAN<br>DTN          | 2020-09-29<br>2023-05-15 |
| Verified / Reviewed by: | Hans Kristian Kofoed                      | Product Owner                    | HKK                  | 2024-02-07               |
| Approved by:            | Lars Vestergaard                          | PA Manager                       | LAV                  | 2024-05-01               |

**Document Change Log (Not mandatory)**

| Revision | Date       | Initials | Description  |
|----------|------------|----------|--|
| 1.0      | 2020-09-29 | SEAN     | Initial release  |
| 1.1      | 2024-02-09 | DTN      | New vibration, shock, irradiation, thermal stress test results added |
| 1.2      | 2024-05-01 | PHK      | Updated with new thermal stress test using the "single peek frame"   |
|          |            |          |  |

**References**

| Reference | Document title   | Document number | Revision, Date       |
|-----------|--|-----------------|----------------------|
| [RD-1]    | GomSpace Qualification Program                               | 1012670         | Rev. 2.3, 2023-03-24 |
| [RD-2]    | gs-qtrp-nanocom-ant2150-dup Mechanical Vibration Test Report | 1050573         | Rev. 1.0, 2023-05-15 |
| [RD-3]    | gs-qtrp-nanocom-ant2150 Mechanical Shock Test Report         | 1054782         | Rev. 1.0, 2023-11-16 |
| [RD-4]    | gs-qtrp-nanocom-ant2150 Thermal Vacuum Test Report           | 1055442         | Rev. 1.0, 2023-12-20 |
| [RD-5]    | gs-qtrp-nanocom-ant2150 TID Test Report                      | 1052937         | Rev. 1.0, 2023-09-19 |
| [RD-6]    | gs-qtrp-nanocom-ant2150 Thermal Stress Test Report           | 1054960         | Rev. 1.1, 2024-03-06 |

## TABLE OF CONTENTS

|                                |    |
|--------------------------------|----|
| 1. QUALIFICATION TESTS .....   | 4  |
| 1.1 PURPOSE.....               | 4  |
| 1.2 PRODUCT.....               | 4  |
| 1.3 VIBRATION TESTS.....       | 5  |
| 1.4 SHOCK TESTS.....           | 6  |
| 1.5 THERMAL VACUUM TESTS ..... | 7  |
| 1.6 RADIATION TID TESTS.....   | 8  |
| 1.7 THERMAL STRESS TEST.....   | 9  |
| 1.8 FLIGHT HERITAGE .....      | 10 |

## 1. Qualification Tests

### 1.1 Purpose

This document describes the environmental qualification tests which is carried out on this specific product(s). In the following sections, the tests and the corresponding test results are described.

### 1.2 Product

Manufacturer Name: GomSpace  
Product Name: NanoCom ANT2150-DUP  
Product Number: 200346

Manufacturer Name: GomSpace  
Product Name: NanoCom ANT2150-ISL  
Product Number: 200347

Both variants are covered by this test since they share the same mechanics, i.e., antenna module, backplates and PCB, where the difference between the two products are the values of a few passive components only.

### 1.3 Vibration Tests

The product has been subjected to the following tests.

**Tests:** Random Vibration  
Sinusoidal Vibration  
Quasi-static / Sine burst

**Conditions:** Product is mounted in a 6U GomSpace structure which is mounted inside a GomSpace Qualification POD. It is tested under the following test conditions.

| Test Description          | Test Conditions   |
|---------------------------|---|
| Random Vibration          | 20Hz, 0.026G2/Hz<br>20-50Hz, +6 dB/oct<br>50-800Hz, 0.16G2/Hz<br>800-2000Hz, -6 dB/oct<br>2000Hz, 0.026G2/Hz<br>Overall, 14.1Grms |
| Sinusoidal Vibration      | 5-8Hz, 10mm p<br>8-100Hz, 4.5G  |
| Quasi-static / Sine burst | 30Hz, 15G,<br>19 cycles / 7 loaded cycles   |

**Remarks:** For details see the NanoCom ANT2150 vibration test report, [RD-2].

**Conclusion:** The NanoCom ANT2150 is tested according to the above-mentioned conditions. The visual mechanical inspection and electrical / functional tests are passed. This certificate ensures that performance, test condition and test equipment are according to GomSpace quality.

## 1.4 Shock Tests

The product has been subjected to the following tests.

**Tests:** Mechanical Shock

**Conditions:** Product is mounted in the fixture for the GomSpace shock bench. The device is exposed to three impacts at each axis, X, Y and Z. It is tested under the following test conditions.

| Test Description               | Test Conditions  |
|--------------------------------|--|
| Shock Response Spectrum (SRS): | 100Hz, 40G<br>1000Hz, 1000G<br>2000Hz, 1500G<br>10000Hz, 1500G<br>+/- 6db from the nominal shock<br>50% of the measured shock shall be above nominal shock |

**Remarks:** For details see the NanoCom ANT2150 shock test report, [RD-3].

**Conclusion:** The NanoCom ANT2150 is tested according to the above-mentioned conditions. The visual mechanical inspection and electrical / functional tests are passed. This certificate ensures that performance, test condition and test equipment are according to GomSpace quality.

## 1.5 Thermal Vacuum Tests

The product has been subjected to the following tests.

|                    |   |
|--------------------|---|
| <b>Tests:</b>      | Thermal Vacuum (TVAC)   |
| <b>Conditions:</b> | Product is mounted in a 6U GomSpace structure, prepared with thermocouples and harness, installed in the TVAC chamber for test. The temperature range defined in the table below refers to the thermal interface of the product during test to ensure its operating temperatures are within specifications. It is tested under the following test conditions. |

| Test Description | Test Conditions   |
|------------------|---|
| Temperature      | -40 to +85°C (Non-Operational + Power ON)<br>-40 to +55°C (Operational, TX Full Power, 100% duty cycle) |
| Pressure         | <1e-5 mbar  |
| Cycles           | 8   |
| Dwell time       | ≥2 hours  |

**Remarks:**  
TX high power (31.8dBm / 100%) up to +55°C interface temperature.  
TX high power (31.8dBm / 50%) up to +65°C interface temperature.  
(In both above conditions board temperature will be below 85°C)

For details see the NanoCom ANT2150 TVAC test report, [RD-4].

**Conclusion:**  
The NanoCom ANT2150 is tested according to the above-mentioned conditions. The electrical / functional tests performed are passed. This certificate ensures that performance, test condition and test equipment are according to GomSpace quality.

## 1.6 Radiation TID Tests

The product has been subjected to the following tests.

**Tests:** Radiation TID (Total Ionizing Dose)

**Conditions:** Product is mounted at plate for TID testing, prepared with harness and necessary logging equipment.  
It is tested under the following test conditions.

| Test Description | Test Conditions                   |
|------------------|-----------------------------------|
| Method           | Direct (Online)                   |
| Rate             | Low dose – 36 to 360 rad(Si)/hour |
| Total dose       | ≥20 krad                          |
| Condition        | Biased at room temperature        |
| Annealing        | ≥24 hours                         |
| Ageing           | ≥168 hours                        |

**Remarks:** Re-flashing the MCU after TID exposure failed. The issue is most likely caused by the charge-pump. Please note that re-flashing of MCU is not possible in orbit and the product will be fully functional up to the 20krad.

After the TID test, the MCU was replaced and proven the remaining components of the product are fully functional and resilient to the level of 20krad.

For details see the NanoCom ANT2150 TID test report, [RD-5].

**Conclusion:** The NanoCom ANT2150 is tested according to the above-mentioned conditions. The electrical / functional tests performed are considered as conditionally passed.

An additional TID test without executing re-flashing after TID exposure is planned.

## 1.7 Thermal Stress Test

The product has been subjected to the following tests.

**Tests:** Thermal Stress (Accelerated Lifetime)

**Conditions:** Product is prepared with thermocouples and installed at the shelf of the Thermal Stress chamber. It is tested under the following test conditions.

| Test Description           | Test Conditions |
|----------------------------|-----------------|
| Temperature – hot plateau  | 100°C +5 /-0°C  |
| Temperature – cold plateau | -55°C +0 /-5°C  |
| Cycles                     | 150             |
| Dwell time                 | 15 minutes      |

**Remarks:** For details see the NanoCom ANT2150 Thermal Stress test report, [RD-6].

**Conclusion:** The NanoCom ANT2150 is tested according to the above-mentioned conditions. The electrical / functional tests performed are passed. This certificate ensures that performance, test condition and test equipment are according to GomSpace quality.

## 1.8 Flight Heritage

The NanoCom ANT2150 is at TRL 9 and has extensive flight heritage at several satellites since June 2017.